

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	183790	sanyo.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 14:49
L2	856222	(mount\$4 attach\$4 affix\$4 fix\$4) near2 (ic die chip dice capacitor transistor resistor diode part component inductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 14:49
L3	99107	((separat\$4 disjoin\$4 dice dicing break\$4) near2 (groove trench channel))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 14:49
L4	2389	L3 near4 (foil conduct\$4 metal metallizat\$ metaliz\$ copper cu)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 14:49
L5	324	L2 and L4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 14:49
L6	224	L5 and (@ad < "20021204")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 14:49
L7	276	L5 and (@ad < "20031201")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 15:35
L8	22	7 and 1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 15:36
L9	6290	((438/124) or (438/770) or (438/665) or (438/617) or (174/260) or (174/261)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/30 16:18

S95	2734	((438/1) or (438/2) or (438/3) or (438/4) or (257/5) or (257/6) or (257/7) or (257/8)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/30 16:58
S96	475200	(conduct\$4 cu copper al aluminum zn zinc pt platinum pd palladium) near2 (foil layer metallization)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/23 11:56
S18 2	8641	plasma near2 (clean\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/29 15:58
S18 3	856222	(mount\$4 attach\$4 affix\$4 fix\$4) near2 (ic die chip dice capacitor transistor resistor diode part component inductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/29 15:58
S18 4	462111	(thin\$6 backgrind\$4 grind\$4 cmp planariz\$4) near4 (foil layer metallization)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/29 16:02
S18 5	53	S183 same S184 and S182	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/29 16:03
S18 6	50	S185 and (@ad < "20021204")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/29 16:04
S18 7	248493	(thin\$6 backgrind\$4 grind\$4 cmp planariz\$4) near4 (foil conduct\$4 metal metallizat\$ metaliz\$)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/29 16:03
S18 8	264369	(thin\$6 backgrind\$4 grind\$4 cmp planariz\$4) near4 (foil conduct\$4 metal metallizat\$ metaliz\$ copper cu)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/29 16:38
S18 9	19	S183 same S188 and S182	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/29 16:03

S19 0	401	S183 same S188 and plasma	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/29 16:04
S19 1	71887	plasma with (foil conduct\$4 metal metallizat\$ metaliz\$ copper cu)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/29 16:04
S19 2	156	S183 same S188 and S191	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/29 16:04
S19 3	124	S192 and (@ad < "20021204")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/29 16:42
S19 4	99107	((separat\$4 disjoin\$4 dice dicing break\$4) near2 (groove trench channel))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/29 16:37
S19 5	2389	S194 near4 (foil conduct\$4 metal metallizat\$ metaliz\$ copper cu)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/29 16:42
S19 6	324	S183 and S195	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/29 16:42
S19 7	224	S196 and (@ad < "20021204")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 14:49